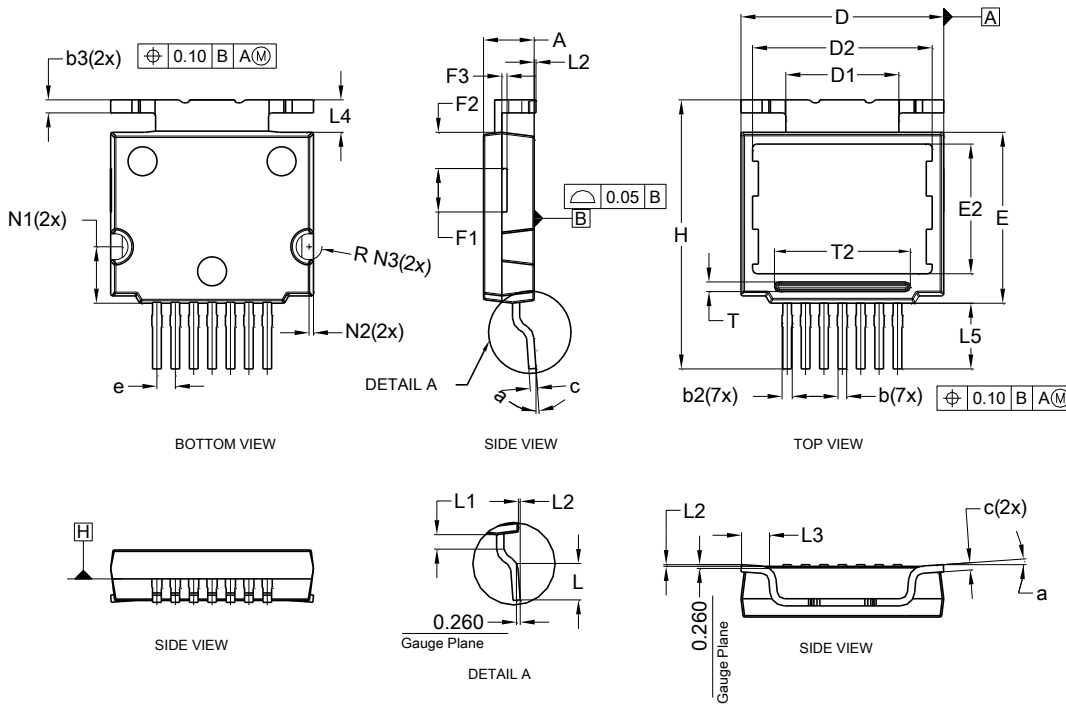


Package Outline Dimensions

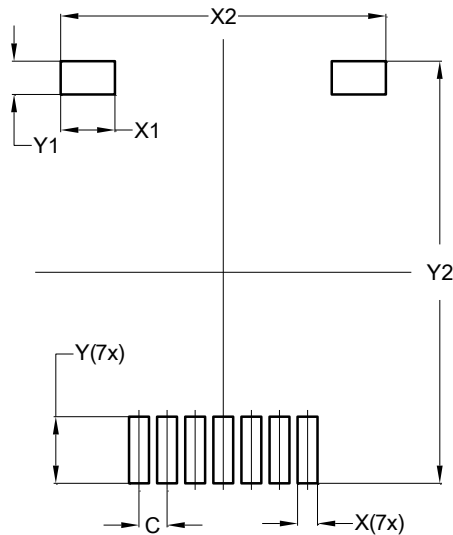
TO263-7 (Type D)



TO263-7 (Type D)			
Dim	Min	Max	Typ
A	3.40	3.60	3.50
b	0.50	0.70	0.60
b2	0.60	0.80	0.70
b3	0.80	1.00	0.90
c	0.40	0.60	0.50
D	13.90	14.10	14.00
D1	7.75	7.85	7.80
D2	12.30	12.50	12.40
e	1.27 BSC		
E	11.70	11.90	11.80
E2	8.80	9.10	8.955
H	18.00	19.00	18.58
L	2.40	2.60	2.52
L1	0.90	1.10	1.00
L2	0.075	0.175	0.125
L3	1.83	2.03	1.93
L4	2.14	2.34	2.24
L5	4.44	4.64	4.54
F1	2.90	3.10	3.00
F2	2.40	2.60	2.50
F3	0.25	0.45	0.35
N1	3.80	4.00	3.90
N2	0.25	0.45	0.30
N3	0.80	1.00	0.90
T	0.50	0.70	0.67
T2	9.18	9.43	9.38
a	0°	8°	4°
All Dimensions in mm			

Suggested Pad Layout

TO263-7 (Type C)



Dimensions	Value (in mm)
C	1.270
X	0.900
X1	2.450
X2	14.700
Y	3.000
Y1	1.500
Y2	19.000

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.